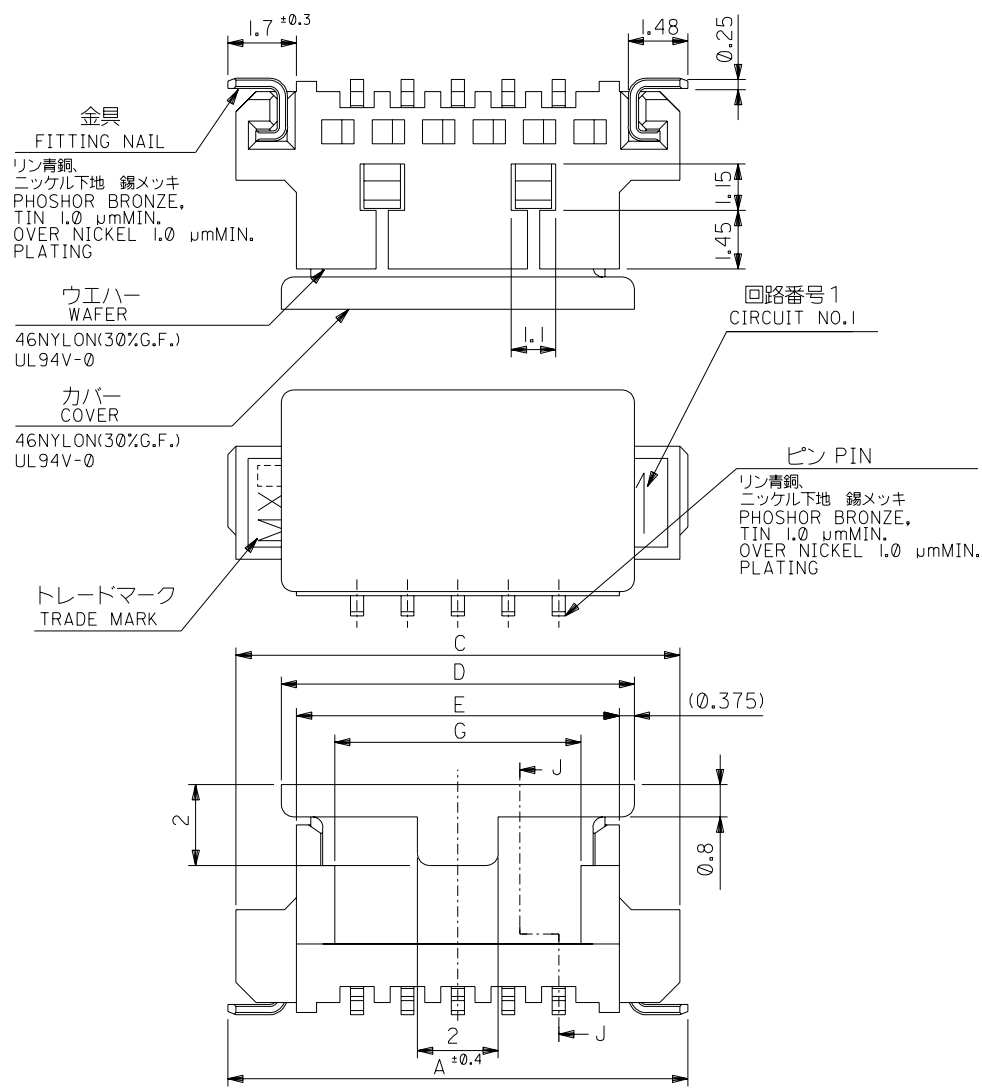
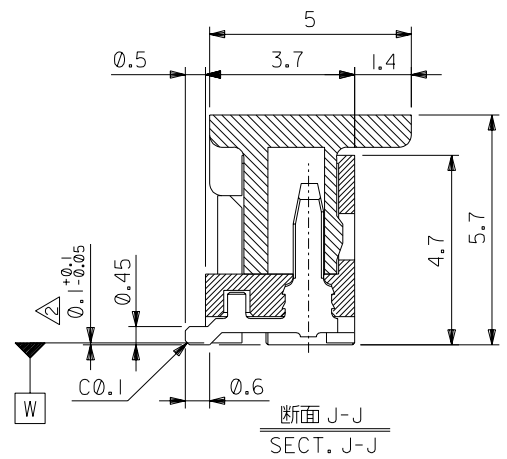


DWG. NO.
SD-53398-034



NOTES

1. 嵌合相手: 51021 シリーズ MATE WITH: 51021 SERIES
2. 水平面上においての、ウェハー底面 [W] とソルダーテール及びフィッティングネイル底面とのズレ量を示す。 MISALIGNMENT OF SOLDER TAIL & FITTING NAIL FROM [W]
3. 偶数極のみ適用。APPLY EVEN CIRCUIT PRODUCTS.
4. 本製品は 53398-**20 の鉛フリー品である。 THIS PRODUCT IS LEAD FREE OF 53398-**20.



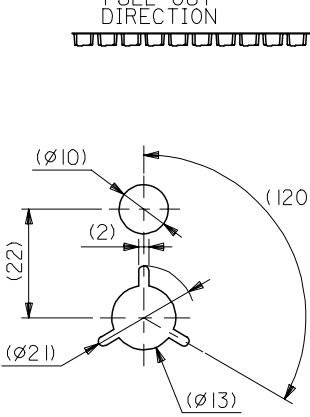
17.35	18.05	19.25	20	22.25	16.25	22.3	53398-1429	14
14.85	15.55	16.75	17.5	19.75	13.75	20.15	53398-1229	12
9.85	10.55	11.75	12.5	14.75	8.75	15.15	53398-0829	8
8.6	9.3	10.5	11.25	13.5	7.5	13.9	53398-0729	7
7.35	8.05	9.25	10	12.25	6.25	12.65	53398-0629	6
6.1	6.8	8	8.75	11	5	11.4	53398-0529	5
4.85	5.55	6.75	7.5	9.75	3.75	10.15	53398-0429	4
3.6	4.3	5.5	6.25	8.5	2.5	8.9	53398-0329	3
2.35	3.05	4.25	5	7.25	1.25	7.65	53398-0229	2
G	F	E	D	C	B	A	MATERIAL NO.	CIRCUITS

DO NOT SCALE DRAWING

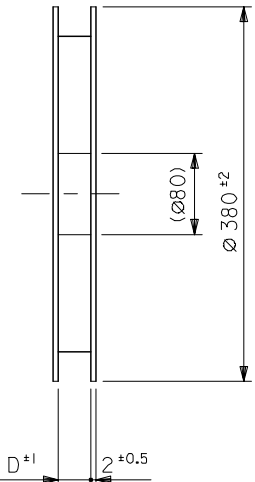
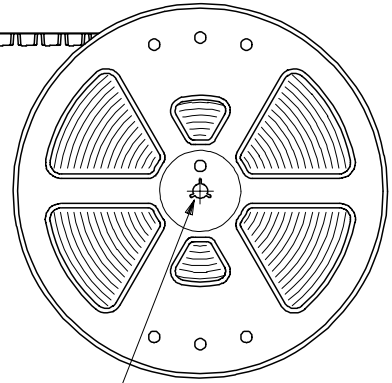
EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. J2004-2404 DRWN: Y.SAKIYAMA CHK: M.SASAO APPR: M.SASAO	RELEASED '04/02/12	MATERIAL 材料 SEE DRAWING	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差 10 UNDER 未満 ±0.2 10 OVER 30 UNDER 未満 ±0.25 30 OVER 以上 ±0.3	SCALE DESIGN UNITS THIRD ANGLE PROJECTION	MODEL NO. 53398-**29	DIMENSIONS: mm INCH mm INCH mm ONLY	SHT REV
					FINISH 仕上げ —		WIRE RANGE 適用電線範囲 —			TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-		
					INS. RANGE 被覆外径 —		ANGLE 角度 ±3°			MATERIAL NO. SD-53398-034.S01	DRAWING NO. SD-53398-034	SHEET NO. 1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.											SIZE B	

SD-53398-034.S01

引き出し方向
PULL OUT DIRECTION

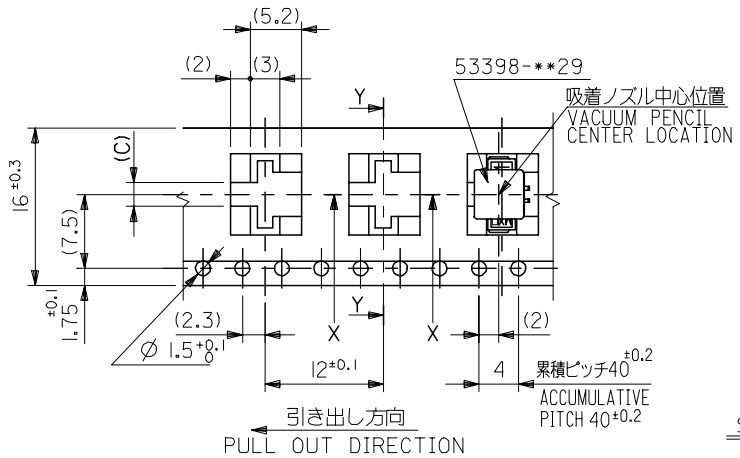
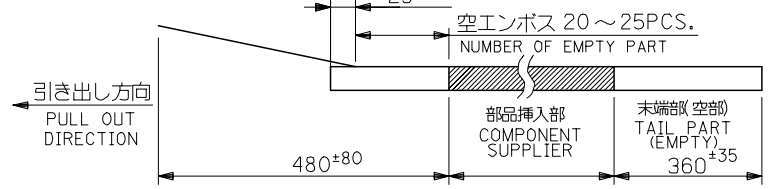


DETAIL "F"



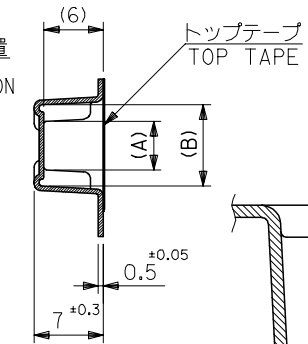
NOTES

- 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH
トップテープ未接着部
TOP TAPE NON-BONDED PART
25±10
空インボス 20~25PCS.
NUMBER OF EMPTY PART
部品挿入部
COMPONENT SUPPLIER
末端部(空部)
TAIL PART (EMPTY)
360±35
480±80
引き出し方向
PULL OUT DIRECTION
- トップテープの剥離強度: 0.6±0.35N(60±35gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE: 0.6±0.35N(60±35gf)
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)
<剥離速度: 300mm/min(参考)>
PEELING SPEED: 300mm/min. (REFERENCE)
剥離方向
PEEL OFF DIRECTION
10°
引き出し方向
PULL OUT DIRECTION
- 53398-***29の詳細寸法については図面 SD-53398-034 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53398-034.
- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は 53398-***80 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53398-***80.

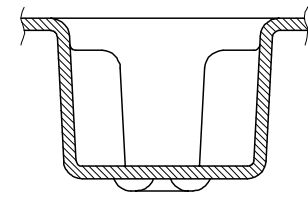


引き出し方向
PULL OUT DIRECTION

16幅テープ
(TAPE WIDTH: 16)



SECT: Y-Y



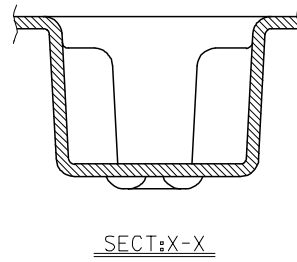
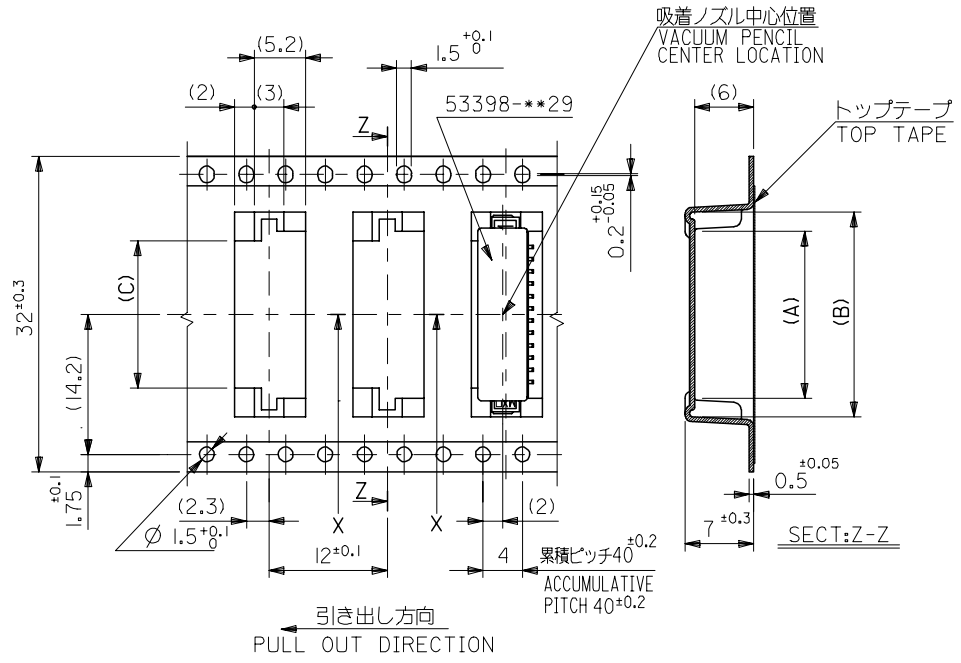
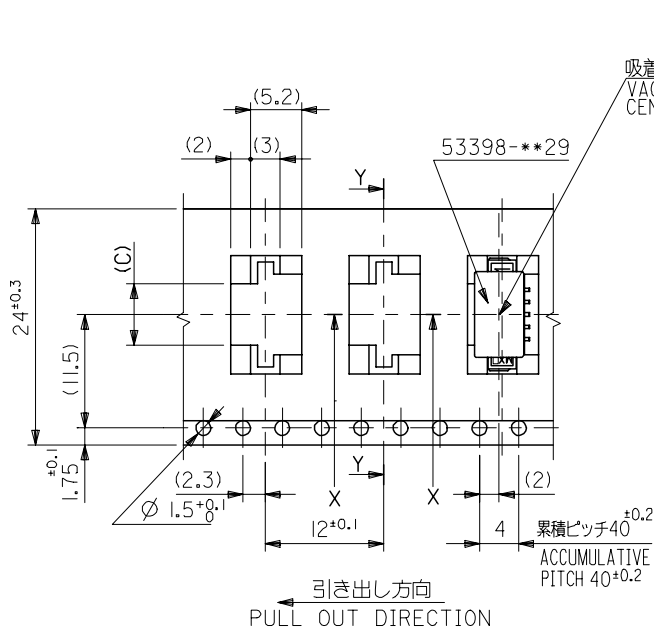
SECT: X-X

32	33.4	14.95	20.75	17.05	53398-1267	12
24	25.4	9.95	15.75	12.05	53398-0867	8
		8.7	14.5	10.8	53398-0767	7
		7.45	13.25	9.55	53398-0667	6
		6.2	12	8.3	53398-0567	5
		4.95	10.75	7.05	53398-0467	4
16	17.4	2.45	8.25	4.55	53398-0267	2
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	MATERIAL NO.	CIRCUITS

REVISED EC NO: DRAWN BY: MERICUCH CHKD BY: ASAKAWA APP'D BY: SICHIKAWA 2004/07/28 2004/07/28 2004/07/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY J. SASAMO	DATE 2004/7/22	TITLE EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/7/22			
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2004/7/22	MOLEX INCORPORATED		
	ANGULAR	±3 °	MATERIAL NO.	DOCUMENT NO. SD-53398-035			
A	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

10 9 8 7 6 5 4 3 2 1

F
E
D
C
B
A



REVISED EC NO: 2004/07/28 DRAWN: M. I. GUCH CHK'D: K. ASAKAW APPR: S. ICHIKAW 2004/07/28 2004/07/28 2004/07/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY J. SASAMO	DATE 2004/7/22	TITLE EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/7/22	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2004/7/22	DOCUMENT NO. SD-53398-035	SHEET NO. 2 OF 2
	ANGULAR	±3 °	MATERIAL NO. SEE CHART			
A	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			